

TSMC-03-130/092



April 9, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/781,169 02/18/04 |

Hsin-Hui Lee et al.

IMPROVING THE UNDERFILLING EFFICIENCY  
BY MODIFYING THE SUBSTRATE DESIGN  
OF FLIP CHIPS

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.


The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
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P.O. Box 1450, Alexandria, VA 22313-1450, on April 12, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 4/12/04

TSMC-03-130/092

U.S. Patent 6,570,261 to Farquhar et al., "Method and Apparatus for Injection Molded Flip Chip Encapsulation," describes an automatic freeway incident detection system and method using artificial neural network and genetic algorithms.

U.S. Patent 5,990,545 to Schueller et al., "Chip Scale Ball Grid Array for Integrated Circuit Package," describes a chip scale ball grid array for integrated circuit package.

U.S. Patent 6,414,849 to Chiu, "Low Stress and Low Profile Cavity Down Flip Chip and Bond BGA Package," describes a low stress and low profile cavity down flip chip and wire bond BGA package.

U.S. Patent Application Publication, US 2002/0011656 A1 to Swanson et al., "Semiconductor Device Protective Overcoat with Enhanced Adhesion to Polymeric Materials and Method of Fabrication," describes a semiconductor device protective overcoat with enhanced adhesion to polymeric materials and method of fabrication. 2

Sincerely,



Stephen B. Ackerman,  
Reg. No. 37761

Doc No: Humber (Cp 2100)

License Number

TSmc-03-130/092 10/781,169

Applicant Hsin-Hui Lee et al.

Filing Date 02/18/04

Group 1st Unit

APR 15 2004

(Use several sheets if necessary)

ТРЕБОВАНИЯ

12/12/12

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DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YTD/SHL
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.